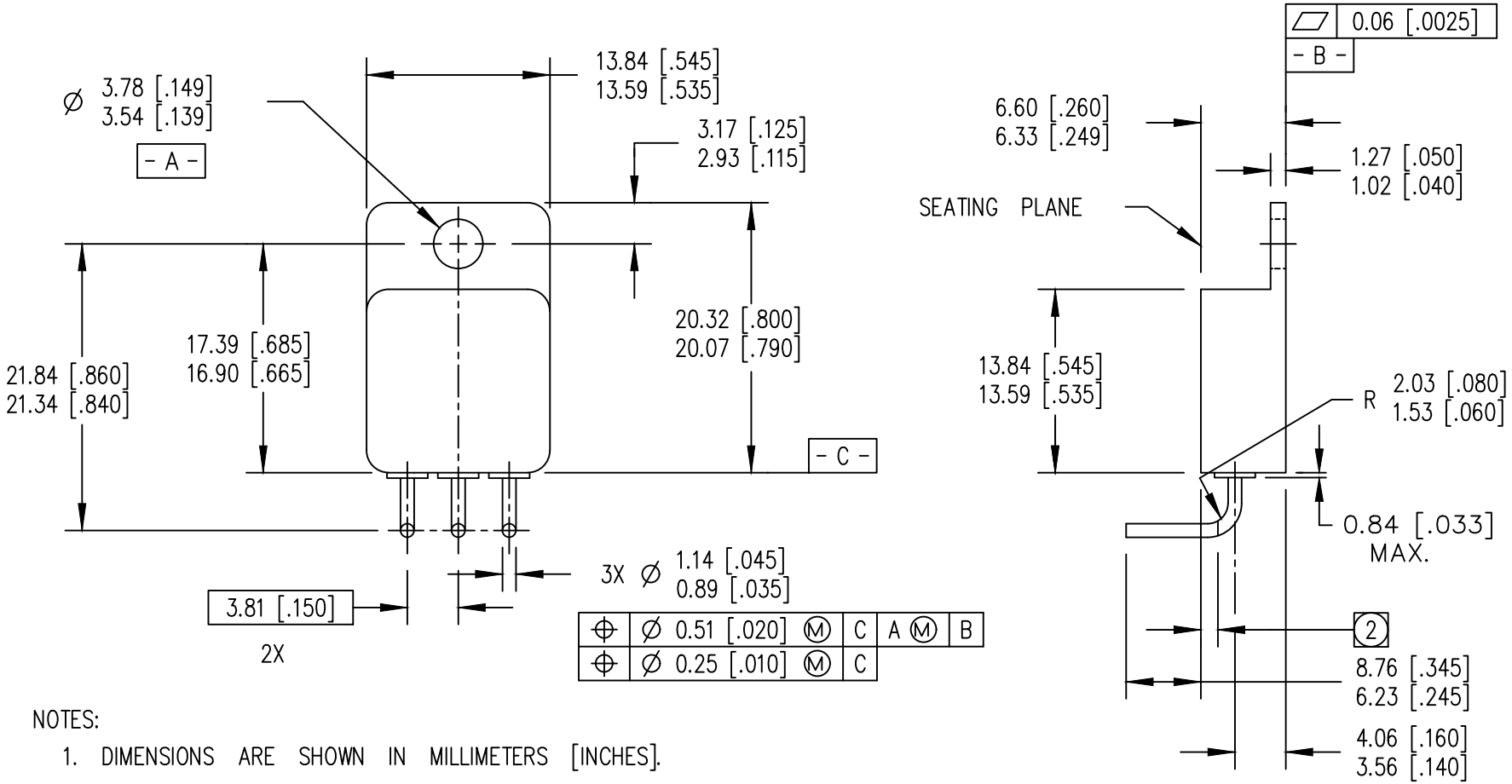
REV.	DESCRIPTION	ECN	DATE
E	CHANGE PER ECN	1120_10056	8–13–24



NOTES:

1. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].

(2) LEADS ARE SOLDER DIPPED 1.27 [.050] MINIMUM BEYOND THE SEATING PLANE.

3. STANDARD FINAL FINISH ON ALL TERMINALS IS SOLDER ALLOY 63%Sn 37%Pb.

IOR HiRel
An Infineon Technologies Company

TITLE: TO-254AA LEADFORM
90° UP, PACKAGE OUTLINE

DRAWING NO. D100708G-WEB

REV E